

I537 Series



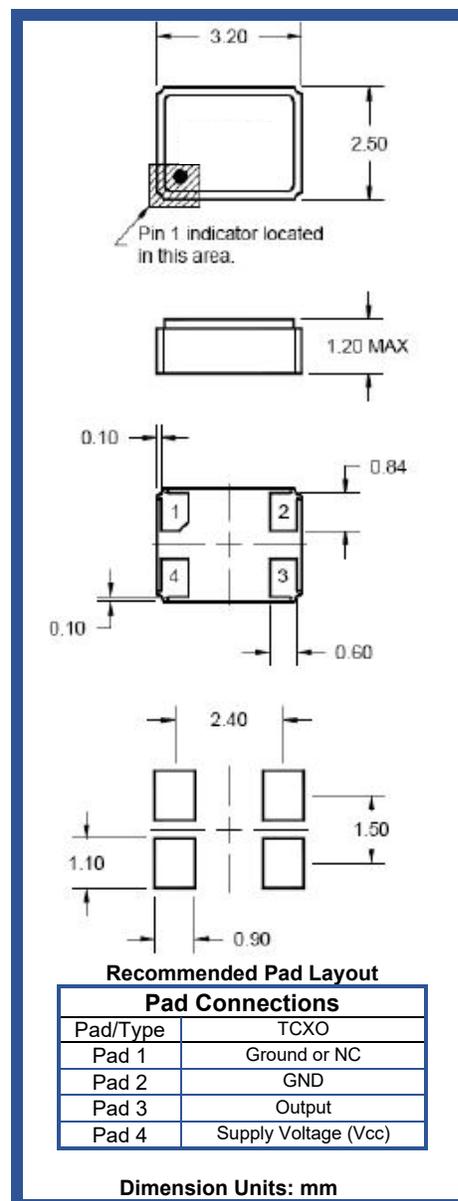
Product Features:

TCXO
 Low Jitter, Non-PLL Based Output
 Clipped Sinewave Output
 Compatible with Leadfree Processing
 Digital Compensation

Applications:

Wireless Communication
 Test Instruments
 GPS
 Base stations
 Telecommunications

Frequency	8.000 MHz to 40.000 MHz
Output Level Clipped Sinewave	0.8 Vp-p Min.
Output Load	10K Ohms // 10 pF
Frequency Stability Vs Temperature Vs Voltage ($\pm 5\%$) Vs Load ($\pm 5\%$)	See Frequency Stability Table ± 0.3 ppm Max. ± 0.2 ppm Max.
Frequency Tolerance @ 25° C	± 1.0 ppm Max.
Aging @ 25° C	± 1 ppm / Year Max.
Supply Voltage	See Supply Voltage Table, Tolerance $\pm 5\%$
Current	2.0 mA Max.
Operating	See Operating Temperature Table
Storage	-40° C to +85° C
Phase Noise (Typ. @ 20Mhz)	-86 dBc/Hz @ 10 Hz -115 dBc/Hz @ 100 Hz -138 dBc/Hz @ 1KHz -146 dBc/Hz @ 10KHz



Part Number Guide		Sample Part Number: I537-1Q3- 20.000 MHz		
Package	Operating Temperature	Frequency Stability vs Temperature	Supply Voltage	Frequency
I537 (Clipped Sinewave TCXO)	7 = 0°C to +50°C	**N = ± 1.0 ppm	2 = 2.7 V	-20.000 MHz
	1 = 0°C to +70°C	**O = ± 1.5 ppm	3 = 3.3 V	
	3 = -20°C to +70°C	P = ± 2.0 ppm	6 = 2.5 V	
	5 = -30°C to +85°C	Q = ± 2.5 ppm	7 = 3.0 V	
	2 = -40°C to +85°C	R = ± 3.0 ppm	8 = 2.8 V	
		J = ± 5.0 ppm		

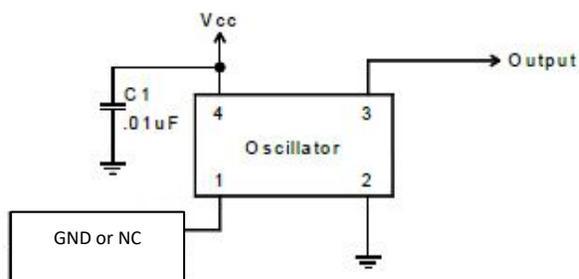
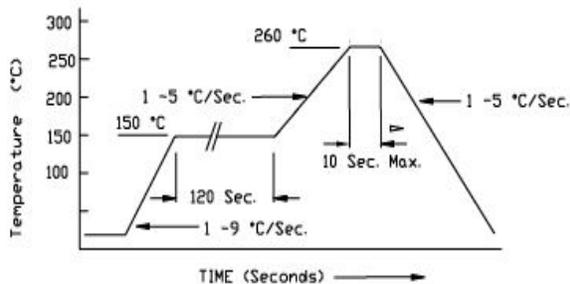
NOTE:

A 0.01 μ F bypass capacitor is recommended between Vcc (pin 4) and GND (pin 2) to minimize power supply noise.

** Not available for all operating temperature ranges and output frequencies.

Pb Free Solder Reflow Profile:

Typical Application:

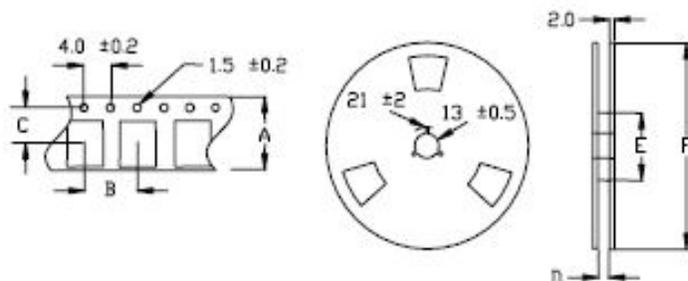


*Units are backward compatible with 240C reflow processes

Package Information:

MSL = N.A. (package does not contain plastic; storage life is unlimited under normal room conditions).
Termination = e4 (Au over Ni over W base metallization).

Tape and Reel Information:



Quantity per Reel	3000
A	8 ± 0.3
B	4 ± 0.2
C	3.5 ± 0.2
D	9±1
E	60 / 80
F	180

Environmental Specifications:

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10 ⁻⁸ atm cc/s
Solvent Resistance	MIL-STD-202, Method 215